SPECIFICATIONS

Basic Specifications

■Diameter of wafer work

4 inti to 8 inti(4-inch is optional)

■Grinding mode

Continuous down feed mode

■Operation mode

Full auto mode
Semi auto mode
Manual mode

■Grinding spindle

1) Bearing	Air bearing (porous carbon)
2) Number of spindles	2 (Coarse and Finish)
3) Motor	2-2 kW 4P, direct coupled type, driven by inverter
4) Motor current	With interlocks and display
5) Cooling method	Air-cooled Water-cooled (optional)
6) Rotation speed	0 to 3600 rpm
7) Maximum vertical stroke	150 mm
8) Grinding speed	1 to 999 um/min
9) Vertical fast-grind speed	200 mm/min
10) Grinder form	250 mm diameter
11) Angle adjustment	Manual Automatic (option)
12) Position setting	Manual Automatic (option)